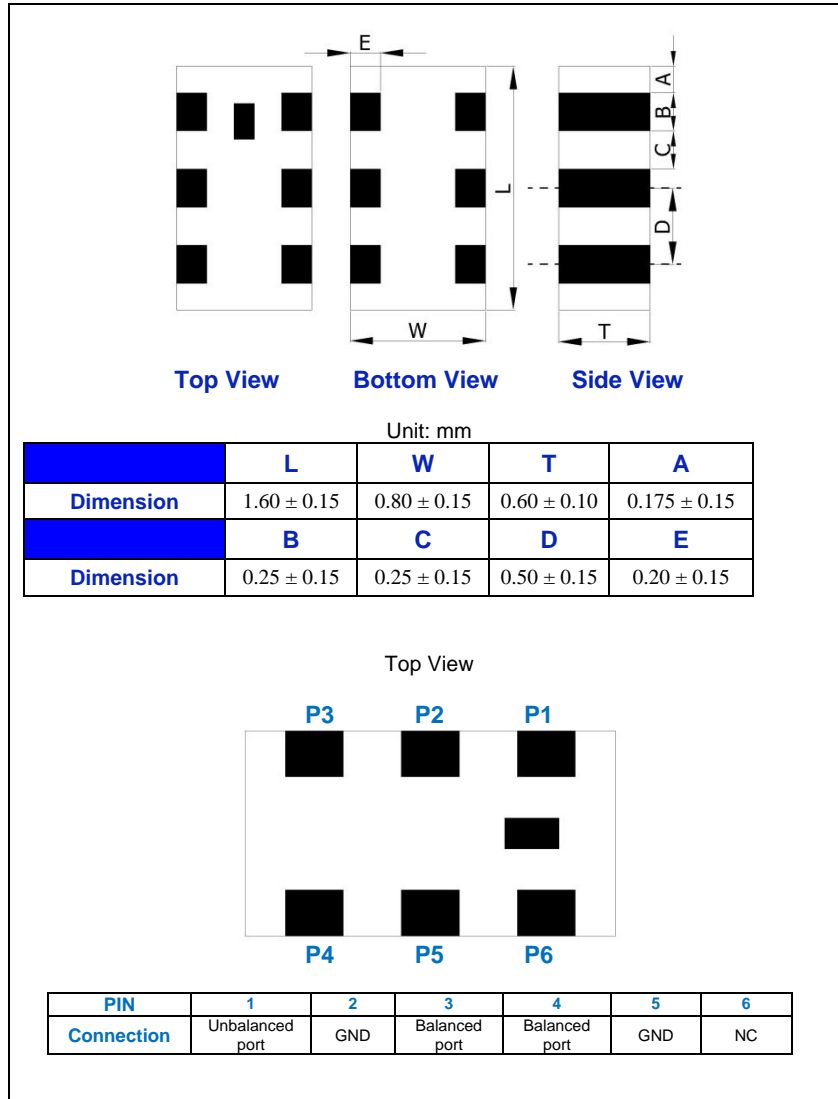


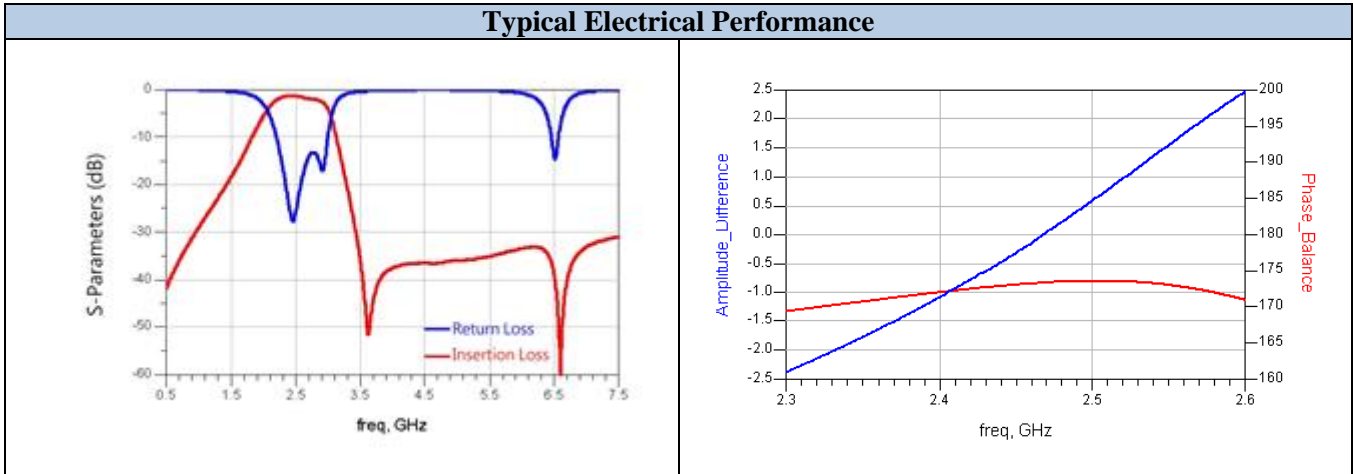
■ ELECTRICAL SPECIFICATION

PARAMETER		SPECIFICATIONS	UNIT
Frequency Range		2400 ~2500	MHz
Insertion Loss, max	@ 25°C	1.6	dB
	@ -40 ~ +85°C	1.8	
Attenuation, min	@ 4800~5000 MHz	25	dB
	@ 7200~7500 MHz	25	
VSWR, max		2.4	-
Unbalanced Impedance		50	Ω
Balanced Impedance		Conjugate match to TI CC26XX chipset	-
Phase Difference		180 ± 18	°
Amplitude Difference, max		2.3	dB
Operating Temperature Range		-40 ~ +85	°C
Moisture Sensitivity Levels		Level 1	

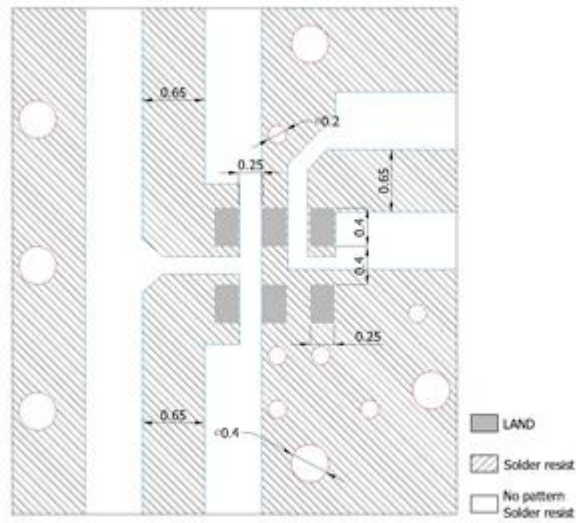
MECHANICAL SPECIFICATION



Typical Electrical Performance



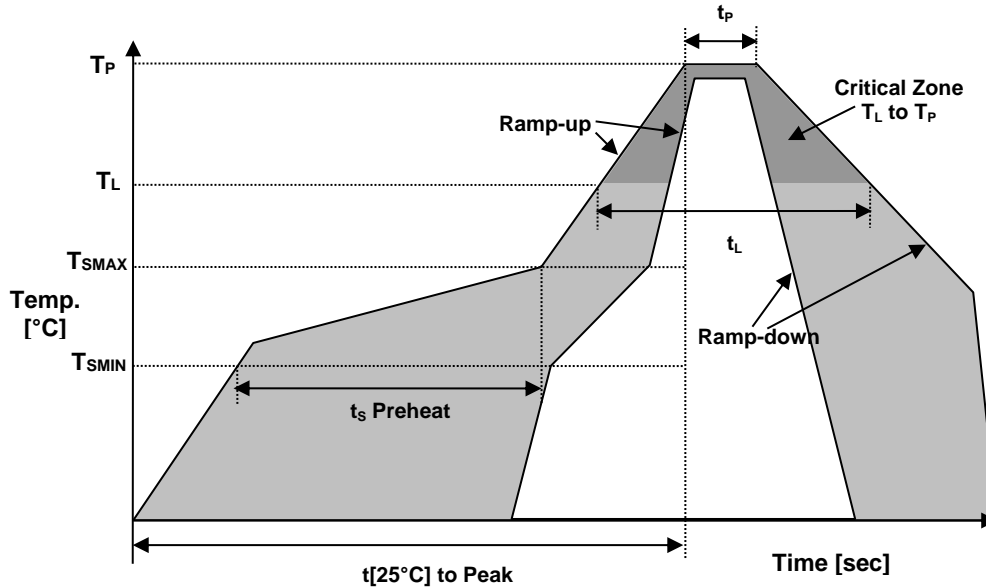
Solder Land Pattern



Unit : mm

Line width to be designed to match 50 Ω characteristic impedance, depending on PCB material and thickness.

REFLOW PROFILE



Reflow profile		
Temperature Min Preheat	T_{SMIN}	150°C
Temperature Max Preheat	T_{SMAX}	200°C
Time (T_{SMIN} to T_{SMAX})	t_s	60-180 sec.
Temperature	T_L	217°C
Peak Temperature	T_P	260°C
Ramp-up rate	R_{UP}	3°C/sec max.
Ramp-down rate	R_{DOWN}	6°C/sec max.
Time within 5°C of Peak Temperature	t_p	10 sec.
Time $t_{[25^\circ\text{C}]}$ to Peak Temperature	$t_{[25^\circ\text{C}]}$ to Peak	480 sec.
Time	t_L	60-150 sec.

ENVIRONMENTAL

PARAMETER	VALUE
MOISTURE SENSITIVITY LEVEL	1
RoHS2	6/6 COMPLIANT & LEAD FREE
REACH-SVHC	COMPLIANT
HALOGEN-FREE	COMPLIANT
TERMINATION FINISH	Sn



March, 2017